

# **Direct Contact Liquid Cooling** on a Project Olympus Server

### Cam Turner, P.Eng. CoolIT Systems Sr Program Manager, Hyperscale Solutions





### **Advanced Cooling Solutions**







## Agenda

- Case study objective
- Overview of the Project Olympus Server
- Server
- Test setup and constants
- Results from testing
- Changes required to support the harmonization effort







#### Specification of the components needed to implement a liquid cooling solution on the Project Olympus





## Objective

Determine the performance and efficiency improvements achieved by using Direct Contact Liquid Cooling on a **Project Olympus 1U Universal Server** as compared to air.







## Open. Together.



## **Project Olympus**





# Project Olympus Server

#### <u>https://www.opencompute.org/wiki/Server/ProjectOlympus</u>









#### **RACK & POWER**

Configuration:

- 2x Intel(R) Xeon(R) Platinum 8168 CPU @ 2.70GHz
- 24x 32GB DIMM
- 1x PCle





# Why The Project Olympus Server?

The Project Olympus Server was chosen for this case study because:

- It is a versatile server designed around modular building blocks  $\bullet$
- It is an OCP Server Project  $\bullet$
- It has an efficient air cooling solution lacksquare













## **Components Required for DCLC Passive Coldplate**

#### 00 00 0 0

 $\sim$ 

Loop (PCL)

**Rack Manifold** 



**Coolant Distribution** Unit







## 되고 PCL Components

The Olympus Server is cooled using several different coldplate technologies...

- Microchannel Coldplate CoolIT RX1 Server lacksquareModules for Intel Skylake CPU's (x2)
- Direct Contact Memory Cooling CoolIT MX4 DIMM  $\bullet$ Liquid Cooling Array











## 되고 PCL Components

The Olympus Server is cooled using several different coldplate technologies...

- Embedded Tube Coldplate CoolIT designed lacksquarecustom low heat density coldplates
- Chassis blind-mate quick disconnects  $\bullet$









## 되고 PCL Specification

### Treating the PCL as a black box, the specification is as follows:

- Nominal Flow Rate: 1.0 L/min  $\bullet$
- Nominal Pressure drop: 4.5 PSI
- Quick Disconnect Diameter: 3mm
- Complies with <u>TCS/DECS wetted material list</u>  $\bullet$







## PCL Direction of Flow







#### **RACK & POWER**





### Manifold Specification

### **Blind-mate Manifold**

Project Olympus has a blind-mate PMDU, so blind-mate liquid connection is also required.

### The manifold specification is as follows:

- Nominal Flow Rate: 42.0 L/min  $\bullet$
- Nominal Pressure drop: 3 PSI  $\bullet$
- Quick Disconnect Diameter = 20mm  $\bullet$
- 25.4mm Nitrile Tubing  $\bullet$
- Complies with <u>TCS/DECS wetted material list</u>  $\bullet$
- Dimensions:  $\bullet$ 
  - 38mm square tube
  - 1905mm tall by 83mm wide  $\bullet$







## Blind-mate power and cooling









### **CDU** Specification

#### CHx80 Rack-mount liquid-to-liquid CDU 4U Rack-mount CDU capable of handling up to 42 Olympus servers. 2U is left open unoccupied

for networking.

### The CDU specification for this setup is as follows:

- Nominal Flow Rate: 42.0 L/min  $\bullet$
- CDU External Pressure Differential: 7.5 PSI  $\bullet$
- Quick Disconnect Diameter = 20mm  $\bullet$
- Total power dissipated in Liquid = ~25kW  $\bullet$
- Approach Temperature = 5C @ W4, Qprimary=65 L/min  $\bullet$
- Complies with <u>TCS/DECS wetted material list</u>  $\bullet$

















## Test Setup and Constants

#### **Constants:**

- Ambient air temperature = 35°C •
- Liquid flowrate = 1.0 L/min •
- Intel PTU Software recording CPU and Memory Temperature
- Thermocouples recording liquid and air temperatures

### Variables:

Secondary fluid temperate ASHRAE W1, W2, W3, W4

- W1 = 17 °C
- W2 = 27 °C
- W3 = 32 °C
- $W4 = 45 \,^{\circ}C$







#### **RACK & POWER**





## Results – CPU Core Temperature







#### **RACK & POWER**





## Results – Memory Temperature







#### Average Memory Junction Temperature



#### **RACK & POWER**





## Margin to Max Operating Temp

Max Temp	Margin to Max (°C)
	28 5
	20.0
Mem	26.2
Low Density	12.0







#### **RACK & POWER**





## **Component Thermal Resistance**















## Server Power Savings





## Open. Together.



#### **RACK & POWER**



**Case Studies** 

## Conclusion

Using the Project Olympus server as an example, CoolIT Systems Direct Contact Liquid Cooling solution was able to:

- Utilize W4 facility water
- Capture over 20 kW of heat in liquid per rack
- Reduce server power consumption by up to 4%, including pumping power
- Maintain a margin of at least 12 °C to maximum operating temperature









# Changes Required for Harmonization

Once the harmonization specification is complete, we anticipate the following changes will need to be made:

- Adopt the OCP Universal Quick Disconnects for both the PCL and the Manifold to CDU interface
- Validate the wetted material list against the OCP specification
- Validate performance with OCP specified transfer fluids
- Ensure operability within the PQ envelope specification









## Call to Action

This case study presents specifications required for CoolIT Systems to enable liquid cooling on a Project Olympus server.

For liquid cooling to reach wide scale adoption in hyperscale data centers, a harmonization effort is underway to enable interoperability between various liquid cooling solution vendors and technologies. That is the goal of OCP's Advanced Cooling Solutions Coldplate workgroup.

Project Wiki with latest specification: <u>https://www.opencompute.org/wiki/Rack\_%26\_Power/Advanced\_Cooling\_Solutions</u>

Mailing list: <u>https://ocp-all.groups.io/g/OCP-ACS-Cold-Plate</u>

Please join the group and help develop the harmonization standards that will enable advanced cooling solutions for OpenCompute solutions.







## Open. Together.



#### **RACK & POWER**



## Questions?

#### **Stay connected with us:**



www.coolitsystems.com



www.linkedin.com/company/coolit-systems-inc.



@coolitsystems



www.facebook.com/coolitsystems



www.youtube.com/user/coolitsystems









#### **RACK & POWER**





# Open. Together.



OCP Global Summit | March 14–15, 2019



